

Abstract

Optoelectronic component having a heat sink

In the case of a radiation-emitting optoelectronic component (1) which is connected to a heat sink (3) and is intended for pulsed operation with the pulse duration D, and in which temperature changes of the optoelectronic component (1) take place with a thermal time constant τ during pulsed operation, the thermal time constant τ is matched to the pulse duration D in order to reduce the amplitude of the temperature changes. In a preferred manner, the thermal time constant τ of the temperature changes of the optoelectronic component during pulsed operation is $\tau \geq 0.5 D$. The amplitude of the temperature changes during pulsed operation and associated fluctuating mechanical loads are thus advantageously reduced.

Figure 1